Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	5	(substrate or PCB or (printed adj (circuit or wiring) adj board)) and (seed with insulat$3) and mask and (metal$5 near pattern$3) and (opening near expos$3)	US-PGPUB	OR	ON	2005/10/12 11:57
S1	1	(liu-po-chih).in.	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/12 08:21
S2	30	"29"/$.ccls. and (PCB or (printed adj (circuit or wiring) adj board)) and seed and mask and metallic and pattern$3 and opening	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/12 08:23
S3	76	"29"/$.ccls. and (substrate or PCB or (printed adj (circuit or wiring) adj board)) and seed and mask and metallic and pattern$3 and opening	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/12 08:24
S4	59	"29"/$.ccls. and (substrate or PCB or (printed adj (circuit or wiring) adj board)) and seed and insulat$3 and mask and metallic and pattern$3 and opening	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/12 08:24
S5	16	"29"/$.ccls. and (substrate or PCB or (printed adj (circuit or wiring) adj board)) and (seed with insulat$3) and mask and metallic and pattern$3 and opening	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/12 08:28
S6	13	"29"/$.ccls. and (substrate or PCB or (printed adj (circuit or wiring) adj board)) and (seed with insulat$3) and mask and metallic and pattern$3 and opening and contact	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/12 08:28
S7	13	"29"/$.ccls. and (substrate or PCB or (printed adj (circuit or wiring) adj board)) and (seed with insulat$3) and mask and metallic and pattern$3 and opening and contact	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/12 08:44
S8	1	"29"/$.ccls. and (substrate or PCB or (printed adj (circuit or wiring) adj board)) and (seed with insulat$3) and (fifth adj mask) and metallic and pattern$3 and opening and contact	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/12 08:30

S9	1	"29"/$.ccls. and (substrate or PCB or (printed adj (circuit or wiring) adj board)) and (seed with insulat$3) and ((first or second or third or fourth) adj mask) and metallic and pattern$3 and opening and contact	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/12 08:31
S10	18	("3471631" | "4902610" | "5055321" | "5519177" | "5741575" | "5745984" | "5956843" | "6034332" | "6127633" | "6217987" | "6248428" | "6251502" | "6261671" | "6274820" | "6274821" | "6378201" | "6461675").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/12 08:36
S11	4	(29/846).ccls. and (substrate or PCB or (printed adj (circuit or wiring) adj board)) and (seed with insulat$3) and mask and metallic and pattern$3 and opening and contact	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/12 08:47
S12	5	(29/825,830,831).ccls. and (substrate or PCB or (printed adj (circuit or wiring) adj board)) and (seed with insulat$3) and mask and metallic and pattern$3 and opening and expos$3	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/12 08:49
S13	5	(29/846,852).ccls. and (substrate or PCB or (printed adj (circuit or wiring) adj board)) and (seed with insulat$3) and mask and metallic and pattern$3 and opening and expos$3	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/12 08:50
S14	7	(174/255,262).ccls. and (substrate or PCB or (printed adj (circuit or wiring) adj board)) and (seed with insulat$3) and mask and metallic and pattern$3 and opening and expos$3	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/12 08:50
S15	1	(427/250,255.7).ccls. and (substrate or PCB or (printed adj (circuit or wiring) adj board)) and (seed with insulat$3) and mask and metallic and pattern$3 and opening and expos$3	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/12 08:51
S16	164	(substrate or PCB or (printed adj (circuit or wiring) adj board)) and (seed with insulat$3) and mask and metallic and pattern$3 and opening and expos$3	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/12 08:51

S17	77	(substrate or PCB or (printed adj (circuit or wiring) adj board)) and (seed with insulat$3) and mask and metallic and pattern$3 and opening with expos$3	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/12 08:52
S18	162	(substrate or PCB or (printed adj (circuit or wiring) adj board)) and (seed with insulat$3) and mask and (metal$5 with pattern$3) and opening with expos$3	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/12 08:52
S19	12	(substrate or PCB or (printed adj (circuit or wiring) adj board)) and (seed with insulat$3) and mask and (metal$5 near pattern$3) and (opening near expos$3)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/12 11:57